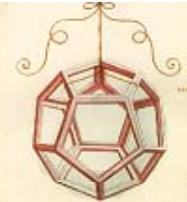


# High precision machining and metrology for structures: achievements and open questions

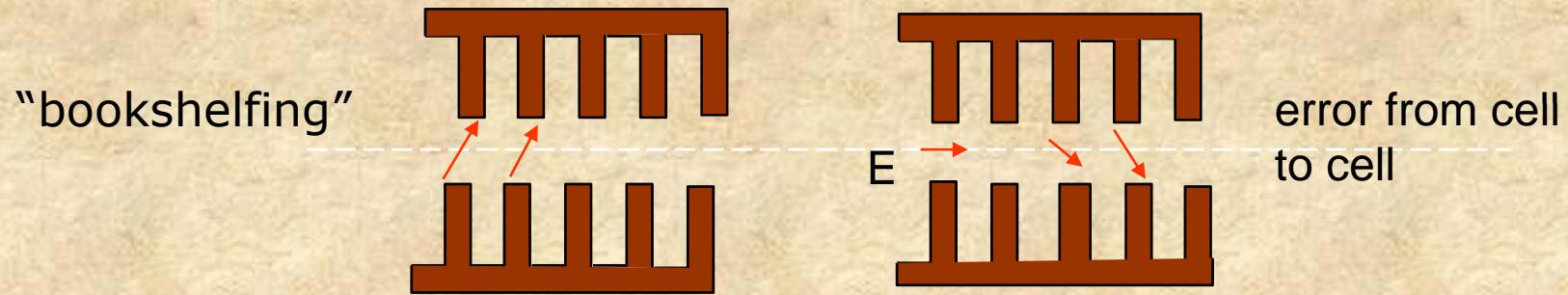
M.Taborelli



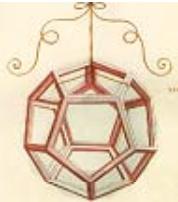
## Why +/- 1 micron precision?



0. Frequency matching (deviation of about  $4\text{MHz}/\mu\text{m}$  on cavity radius at 30 GHz)
1. Longitudinal alignment precision :  $<5\ \mu\text{m}$   
alignment error of the irises induces transversal kick on the beam (depends on iris aperture)

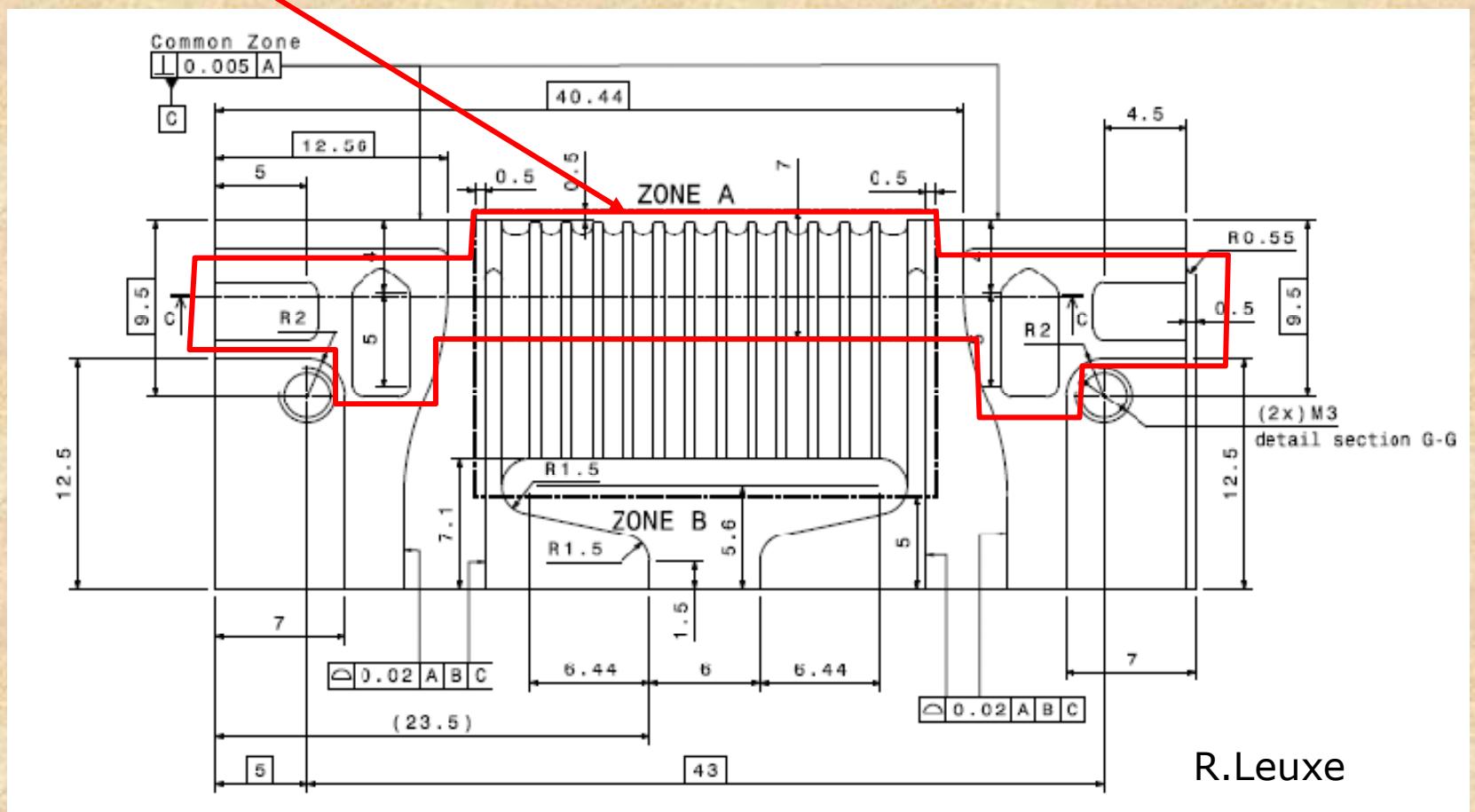


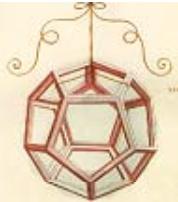
2. Avoid steps and kinks on the surfaces (field enhancement  $\beta$ )
3. Ra should be around  $\frac{1}{4}$  of the skin depth to preserve electrical conductivity ( $0.1\ \mu\text{m}$ )



## Tolerances:

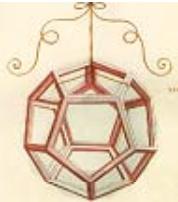
5  $\mu\text{m}$  shape tolerance





## **Ways to approach target accuracy:**

1. Production of structures at “acceptable” precision for CTF3/SLAC high power RF-testing (target +/- 0.01 mm on the shape) and exploit the learning curve of firms (Greenfox, Imtec, VDL....)
  
2. R&D Projects:  
KERN,  $\mu$ -2010 project, EIG, Fraunhofer Inst. ?



## Ongoing projects

KERN Feinwerktechnik (D): (CERN order June 2006)

- Machine tool manufacturer (best accurate commercial milling centers in Europe)
- Produced a first prototype (now at CERN metrology), second improved version will follow
- CERN investment: 15K€ + materials

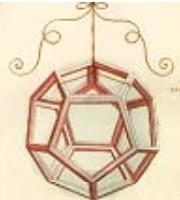
$\mu$ -2010: (start March 2007)

- group of French firms/institutes including ENSAM-Cluny and Mikron-France (machine tool manufacturer)
- will deliver a prototype end of July
- CERN investment: materials, investments for further phase to be discussed

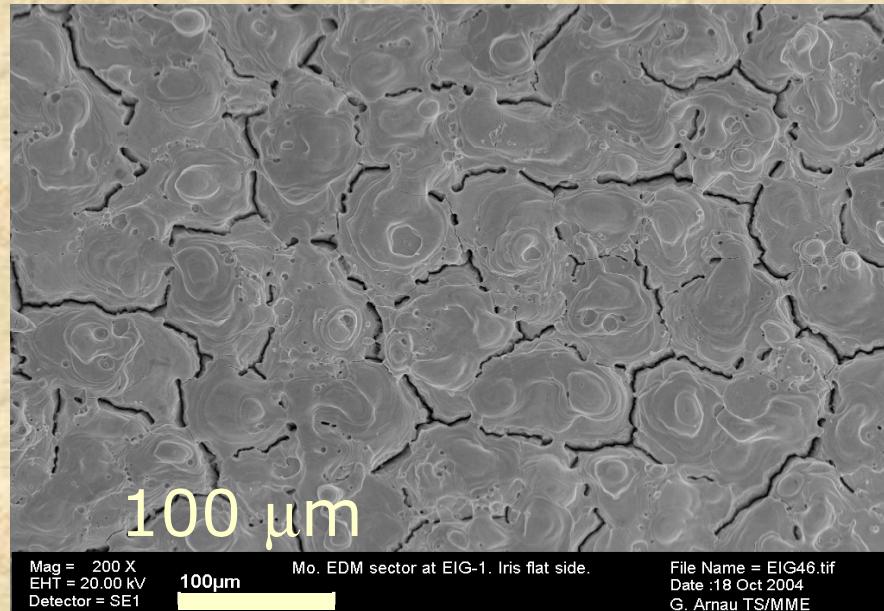
HES-SO Genève: (start Feb 2007, 1y)

- EDM machining and surface finishing of refractory metals
- CERN investment: 20 KFr+ materials

## EDM :

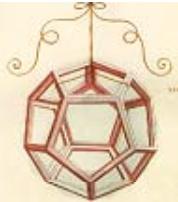


-Electro discharge machining of refractory metals  
( micro-cracks on molybdenum), development in progress



HES-SO Geneva

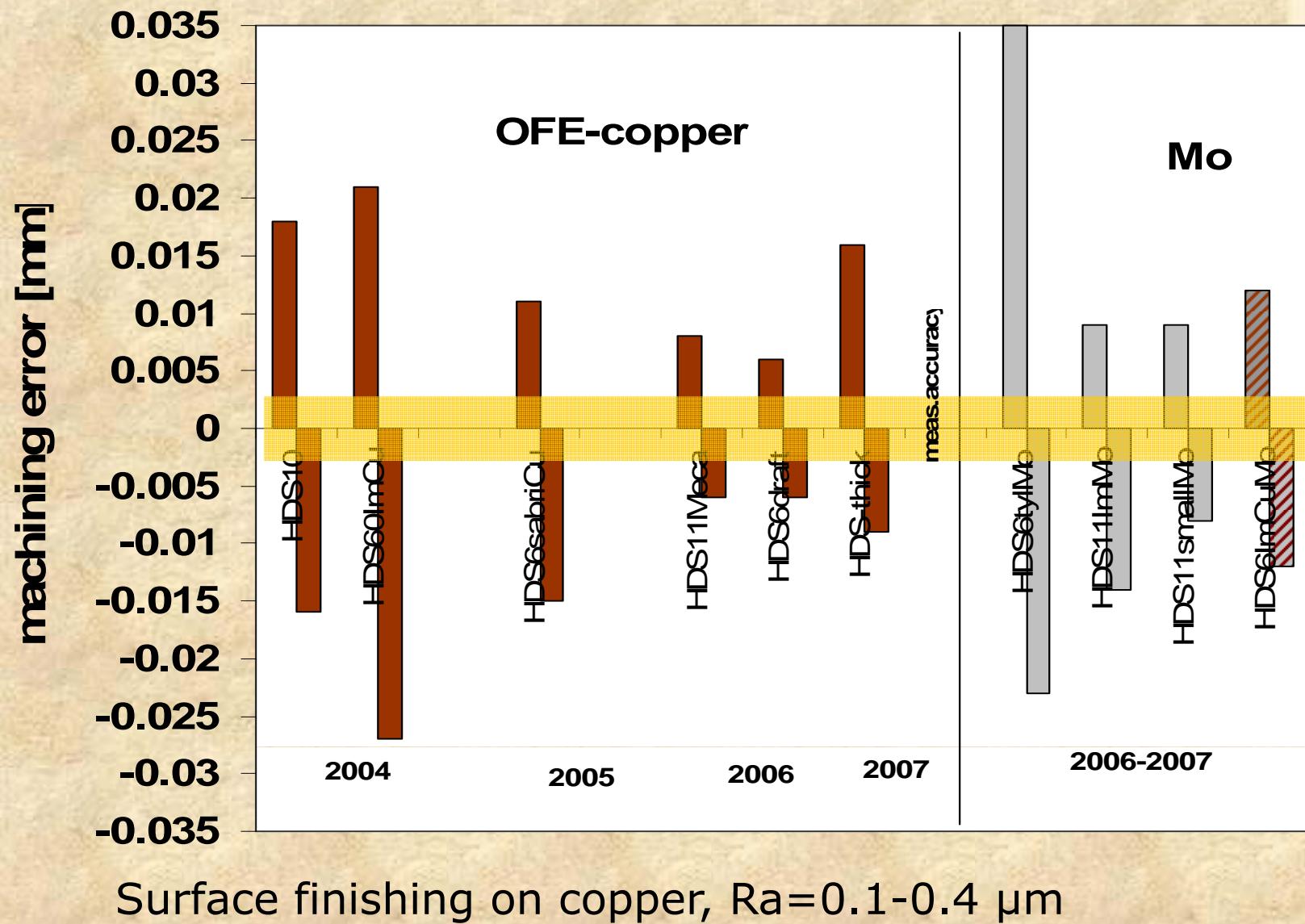
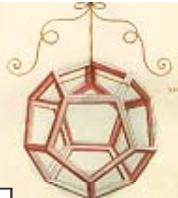
- Parameters to avoid cracks on W are already determined
- Difficult to work in water (black layer); verify the possibility to get clean surfaces when working in oil

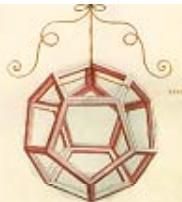


## Machining technology applied so far to manufacture structures

- technology used so far: CNC milling, at high cutting speed (spindles at 20000-50000 rpm)
- positioning accuracy of the machine tools is 5 µm, two machines below 1 µm (range ~300 mm-500 mm)
- carbide or diamond (on copper only) tools (ball nose mills)

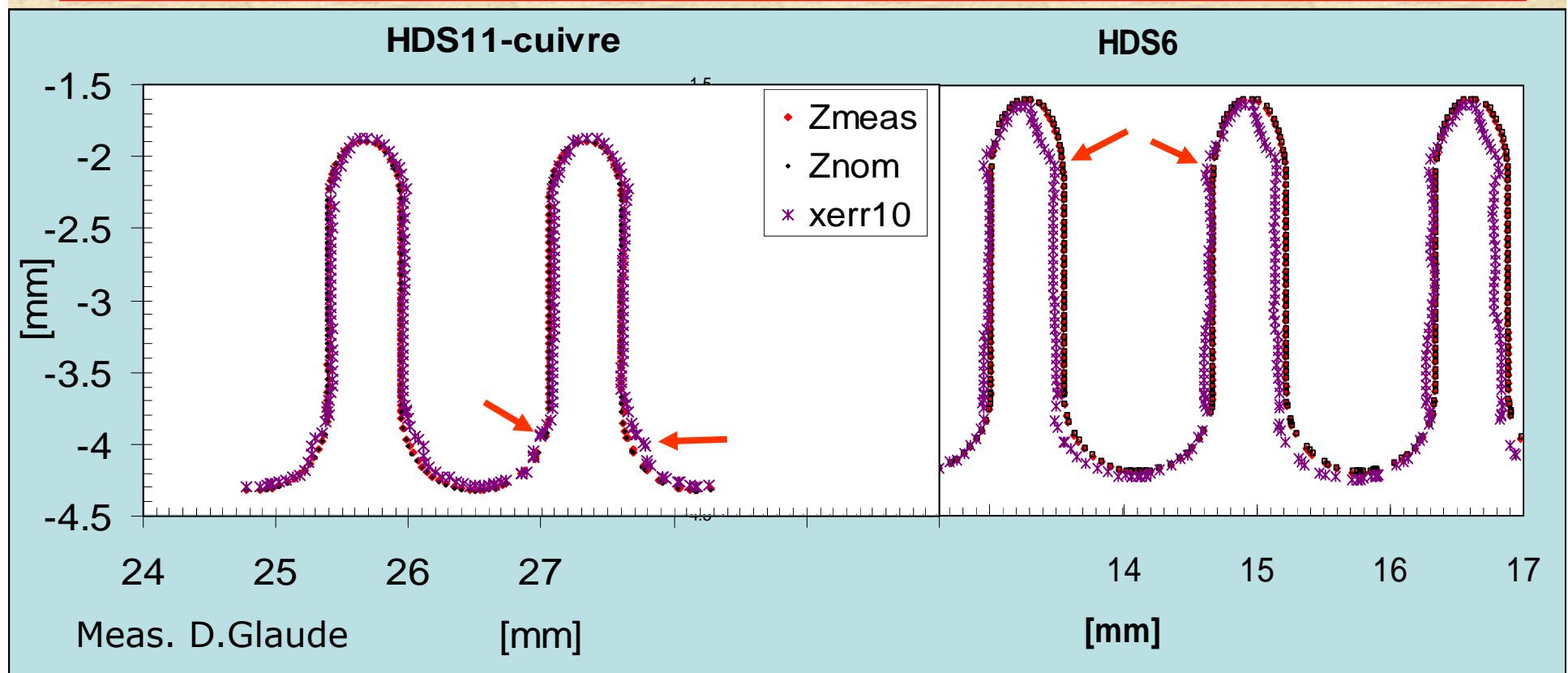
## Achieved shape accuracy

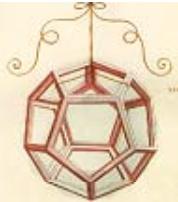




## Metrology on copper quadrants

Measurement: coordinate measuring machine, contact with 0.1N force, accuracy  $\pm 3 \mu\text{m}$  (at CERN), scan pt. by pt. on the surface .....in parallel with RF low power control

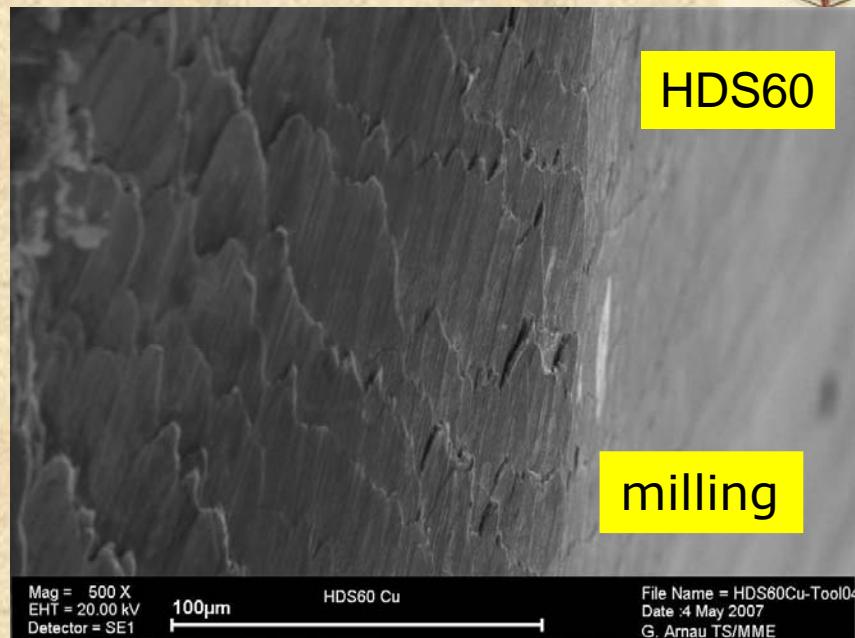
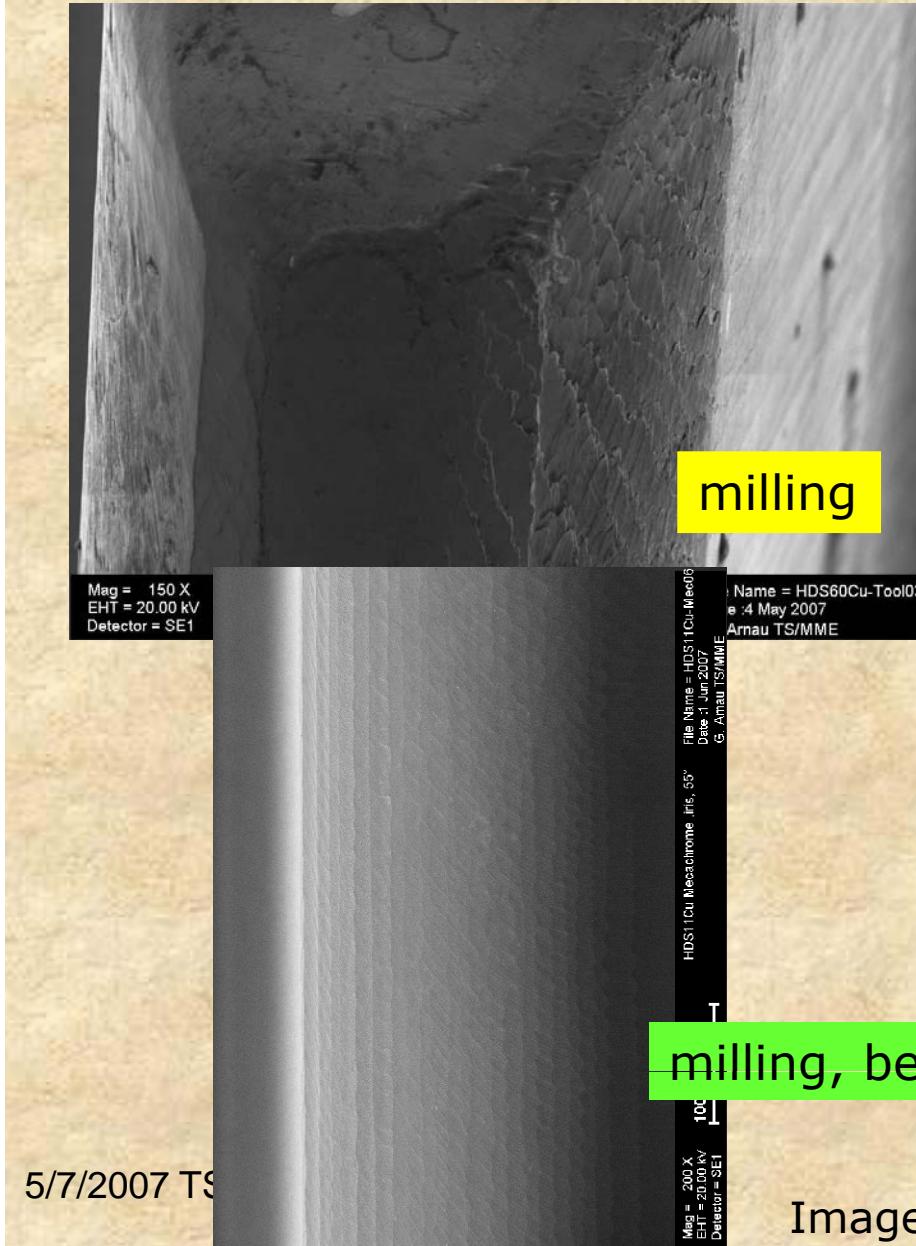
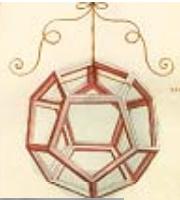




## Possible sources of the error in 3D milling

- Most important:** Error on tool diameter, tool length, tool run-out (dynamic dimensions)
  - Error on tool shape
  - Tool flexure (larger tools at 12GHz should be favourable)
  - Tool consumption during machining
- 
- Temperature stability and dynamics of the machine tool
  - Positioning accuracy of the machine tool (machine tools with higher nominal accuracy have given better surface finish)

# Surface quality: on copper



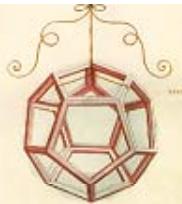
milling, best result

Image: G. Arnau-Izquierdo



Surface quality  
still worse than  
diamond  
turning

M.Taborelli, TS-MME

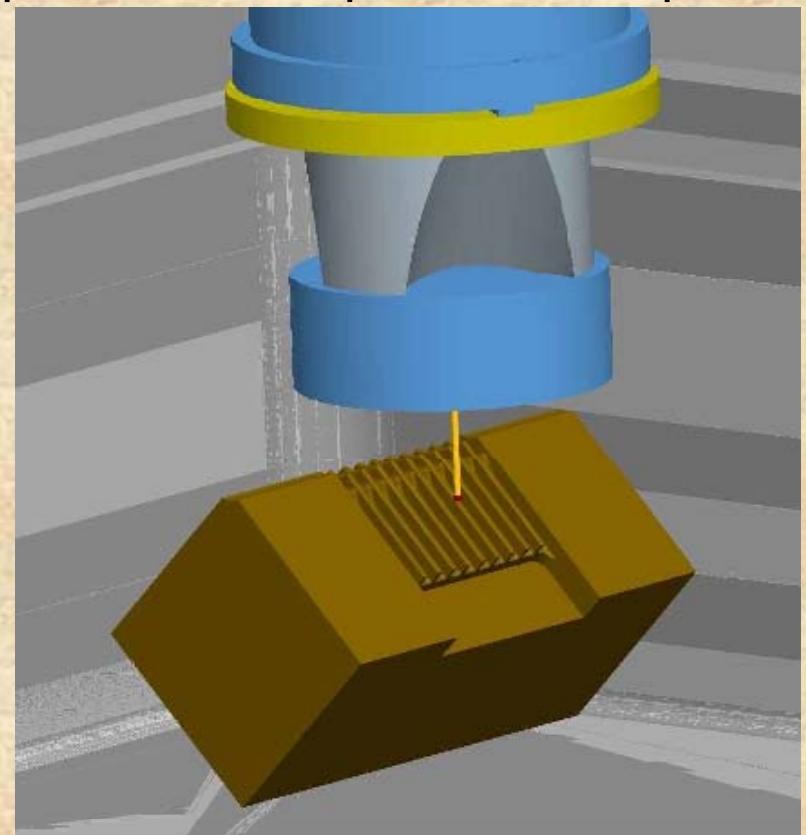
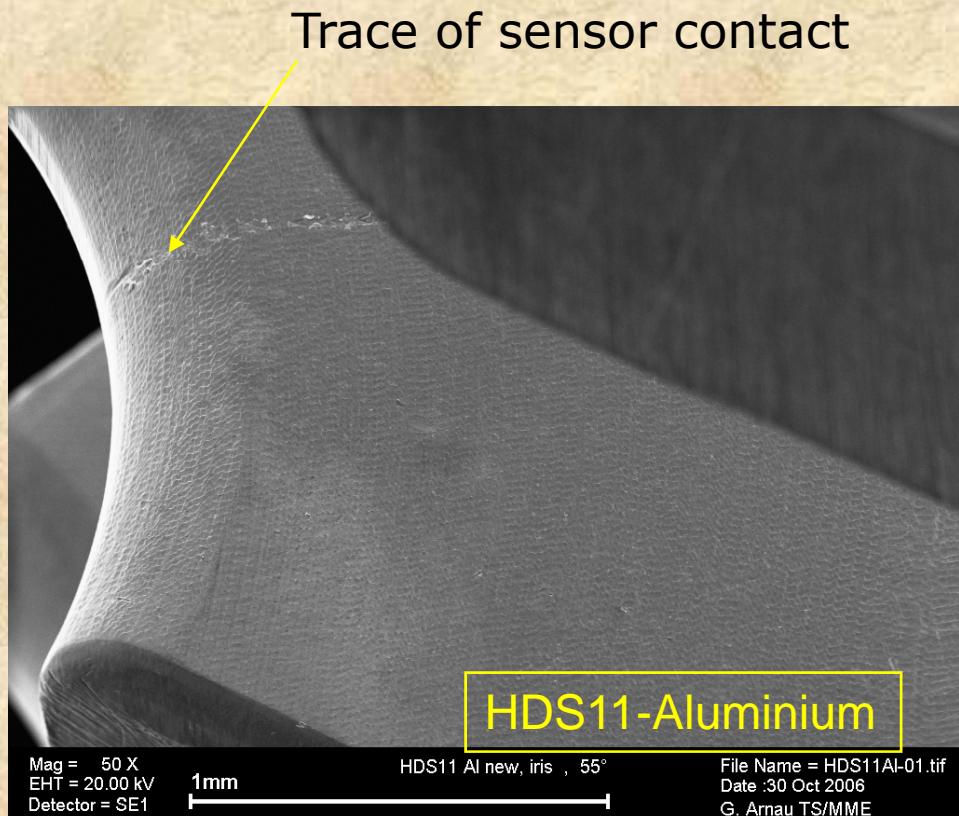


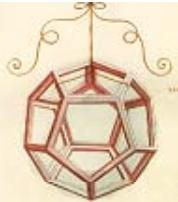
## Metrology

Requires high accuracy, ideally  $0.1 \mu\text{m}$  to control at  $1 \mu\text{m}$  level

Force of the sensor should be low ( $0.1 \text{ N}$  leaves marks)

Available optical methods are not adapted for complex 3D shapes





## Conclusions:

- Realistic goal for 2010 should be to demonstrate +/- 3-5 µm on a copper structure of 250-300 mm (CLIC size)
- +/- 1 µm needs major R&D investment and the market is still marginal for parts of this size
- Improving internal competence for high precision machining is necessary: through follow up, training or doing
- Internally we do not have a metrology equipment to control reliably below +/- 5-10 µm accuracy: needs better sensor (lower forces) and better CMM (higher positioning accuracy)
- Manpower for metrology is limited and feedback cannot be given fast to firms